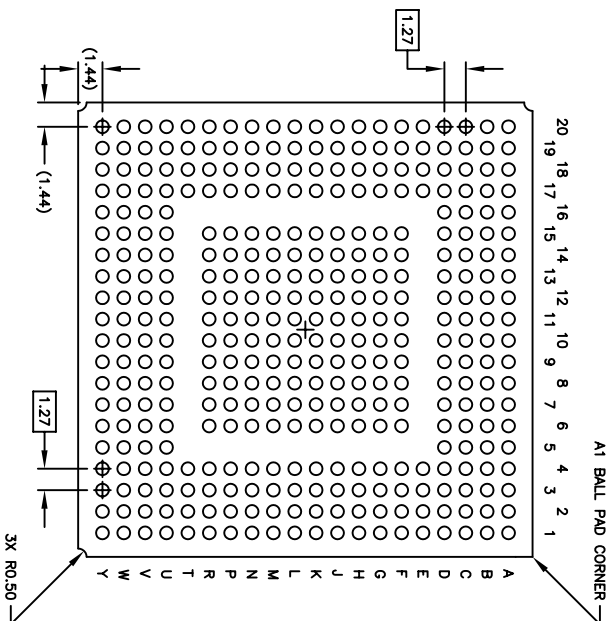


NOTES: UNLESS OTHERWISE SPECIFIED

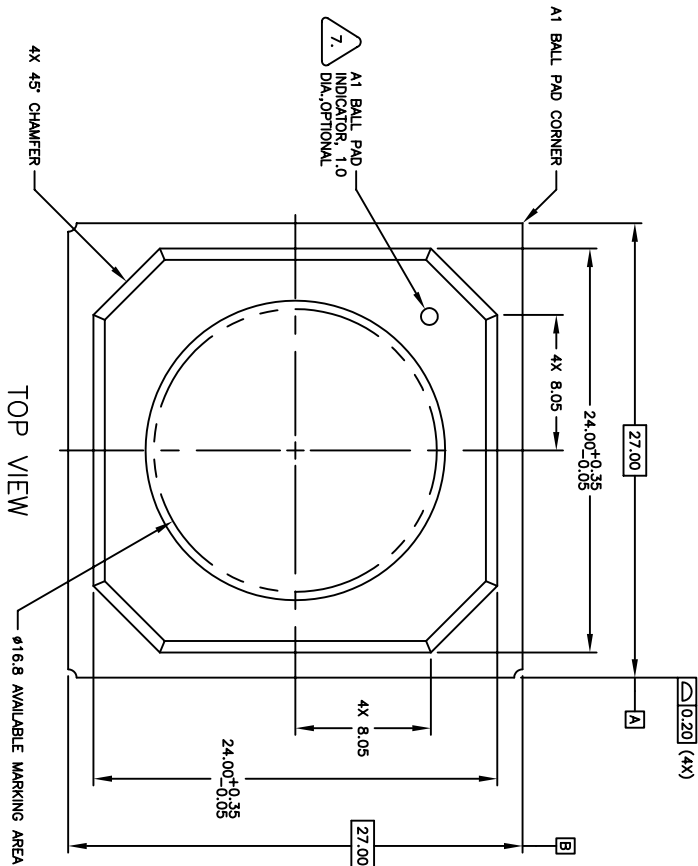
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
2. THE BASIC SOLDER BALL GRID PITCH IS 1.27mm.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 20 X 20.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 400.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

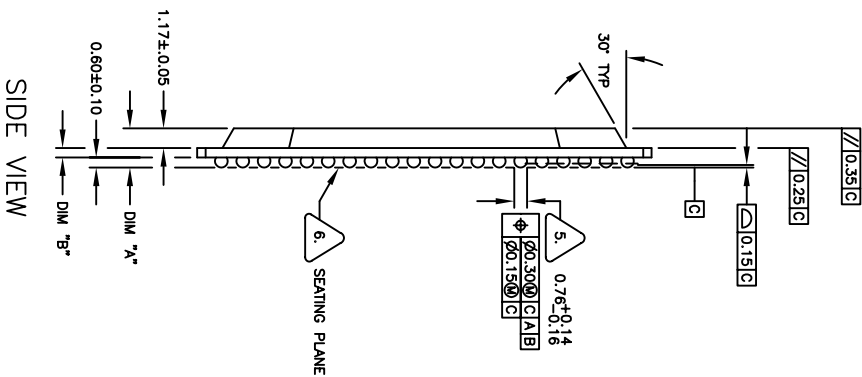
7. A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK; AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP. REFERENCE SPECIFICATIONS: A. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A VARIATION BAL-2.



BOTTOM VIEW
356 SOLDER BALLS



TOP VIEW



SIDE VIEW

Drawing#: V356.27x27A
Rev: 0
Date: 2/28/06
Units: mm

PACKAGE OUTLINE DRAWING - 356 HPBGA
27 x 27 mm x 1.17 mm MOLD CAP
1.27 mm PITCH SUBSTRATE

NO. LAYERS	DIM "A"	DIM "B"	NOTES
4	2.38±0.21	0.61±0.06	STANDARD
HPBGA THICKNESS SCHEDULE			